

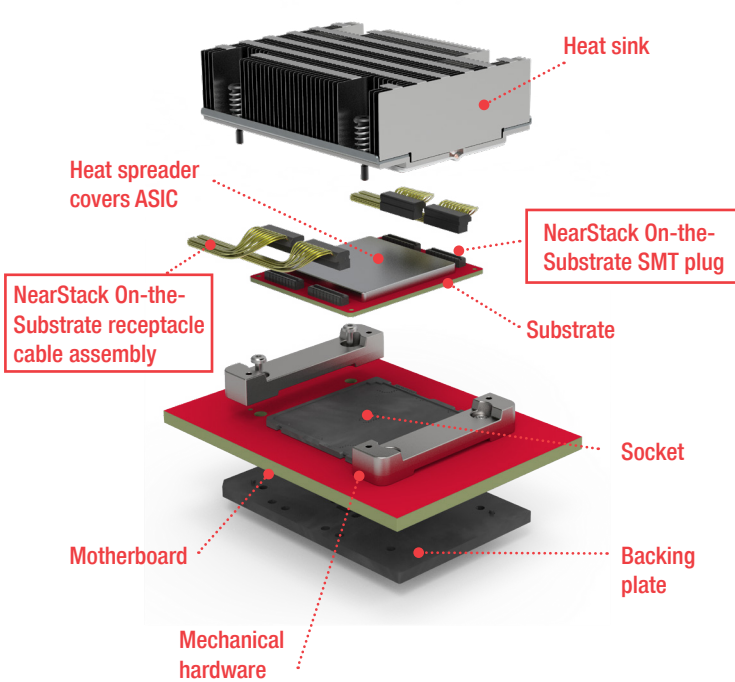
PRELIMINARY

NearStack On-the-Substrate Connector System



Molex's NearStack On-the-Substrate delivers a twinax communication channel superior to PCBs with excellent signal integrity and low insertion loss while enabling implementation of 56 and 112 Gbps PAM-4

Features and Advantages



Plug designed to utilize typical substrate underfill adhesive after SMT and cleaning process

Facilitates capillary action to draw adhesive under connector bonding connector to substrate

Stainless steel pressure plate on top of receptacle

Distributes load from integrated heatsink spring retention



Optimized internal shielding/ground structure
Creates significant signal integrity benefit at higher frequencies

Applications

Telecommunications/Networking

- Top-of-the-rack switches
- Core routers

Data Centers

- Switches
- Servers



Data Center Switches



Servers

NearStack On-the-Substrate Connector System



Target Specifications

REFERENCE INFORMATION

Packaging: SIP-FQC-211934-AC-002
UL File No.: TBD
CSA File No.: TBD
Mates With: 211935
Use With: N/A
Terminal Used: N/A
Designed In: Millimeters
RoHS: Yes
Halogen Free: Yes
Glow Wire Capable: Yes

ELECTRICAL

Voltage (max.): 30V AC RMS
Current (max.): 0.3A
Contact Resistance (max.): 30 m Ω
Dielectric Withstanding Voltage: 300V AC RMS
Insulation Resistance (min.): 10 M Ω

MECHANICAL

Contact Insertion Force: 2N/dp
Contact Retention to Housing (min.): 850g
Insertion Force to PCB: N/A
Mating Force: 2N/dp (no latches)
Unmating Force (min.): 15.6N
Durability (min.): 200 cycles

PHYSICAL

Housing: E130i
Contact: C70250
Plating (min.):
 Contact Area — 1.27 Microns Au
 Solder Tail Area — 2.54 Microns Matte Sn
 Underplating — 1.27 Microns Matte Ni
PCB Thickness: N/A
Operating Temperature (max.): 5 to +40°C Ambient,
70°C Internal

Note: Molex reserves the right to delay or cancel production of the depicted product without additional notice. Please contact your Molex customer service representative for product availability.

www.molex.com/link/nearstack.html

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